

CLAIMS

We claim:

1. A semiconductor package comprising:
a semiconductor die having first and second sides, a first electrical terminal being located on the first side, at least a second electrical terminal being located on the second side; and
a leadframe in electrical contact with the first terminal, the leadframe being formed in the shape of a cup, the die being located in the cup, at least one lead of the leadframe containing a portion that is coplanar with the second side of the die.
- 10 2. The semiconductor package of Claim 1 further comprising a layer of conductive cement located inside the cup between the first terminal and the leadframe.
- 15 3. The semiconductor package of Claim 2 wherein the conductive cement comprises conductive epoxy.
4. The semiconductor package of Claim 1 further comprising a plastic capsule in contact with an outside of the cup.
- 20 5. The semiconductor package of Claim 4 wherein the die is in electrical contact with a bottom of the cup, an outside of the bottom of the cup being exposed.
6. The semiconductor package of Claim 1 further comprising a plastic material located inside the cup between an edge of the die and the leadframe.
7. The semiconductor package of Claim 1 wherein the semiconductor die comprises a MOSFET.
- 25 8. The semiconductor package of Claim 1 wherein the semiconductor die comprises an integrated circuit.

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